PRODUCT SPECIFICATIONS

BAREBONE XPC slim DH610S

ROBUST 1.3-LITRE SLIM PC SUPPORTS INTEL CORE GEN. 12/13 PROCESSORS AND TWO UHD DISPLAYS

The Shuttle XPC slim Barebone DH610S with H610 chipset houses the performance of Intel's 12th/13th generation Core desktop processors (codenamed Alder Lake-S and Raptor Lake-S) for socket LGA1700 in a compact 1.3-litre format. The DH610S allows for two Ultra HD displays to be operated at the same time via HDMI and DisplayPort. It also offers Intel LAN, eight USB ports and Audio ports. The slim metal chassis provides versatile connectivity and reliable operation in environments with ambient temperatures of up to 50 °C. This platform is targeted at professional applications such as Digital Signage, POS, POI, gambling machines, office, healthcare and industry.











2.5" HDD/SSD ALWAYS-ON- REMOTE POWER

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2x 32 GB SUPPORT 1x HDMI 2.0b PORT 1.4



JUMPER SUPPORT

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CONNECTORS

POWER SUPPLY

External 120W/19V power adapter

OPTIONAL ACCESSORIES

(WWN03) ■ VESA Mount (PV04)

STORAGE - SATA / M.2

USB BUTTON Type-C

■ 1x 2.5" bay for SATA hard disk or SSD ■ 1x M.2-2280M slot (supports

PCIe 3.0 x4 NVMe or SATA) 1x M.2-2230E for optional WLAN module

■ 1x HDMI 2.0b ■ 1x DisplayPort 1.4 ■ optional VGA ■ 2x audio (line

out, mic) ■ 4x USB 3.2 Gen1 (1x Type-C) ■ 4x USB 2.0 ■ RJ45 LAN-Port

(Intel 1G) ■ Connector for external power button ■ "Always on" Jumper

■ WLAN Module (WLN-M (ac)/WLN-M1 (ax)) ■ Vertical Stand (PSO2)

■ VGA Port (PVG01) ■ Rackmount kit (PRM01) ■ Cable for external

power button (CXP01)
DIN-Rail mounting kit (DIR01)
LTE-kit





SLIM DESIGN

■ Slim 1.35-litre metal chassis, black ■ Dimensions: 190 x 165 x 43 mm (LWH) ■ Supports 24/7 Nonstop Operation ■ Operating temperature: 0~50 °C (non-condensing)

OPERATING SYSTEM

- An operating system is not included
- Supports Windows 10, Windows 11 and Linux (64-bit)

PROCESSOR SUPPORT **)

Socket LGA1700 supports Intel Core i9/i7/i5/i3, Pentium Gold and Celeron processors Gen. 12 "Alder Lake-S" and Gen. 13 "Raptor Lake-S", max. 65W TDP Includes heatpipe cooling system

GRAPHICS

Integrated Intel HD graphics, 4K support (features depend on processor) Supports two independent UHD displays

CHIPSET

Intel H610 Chipset

MEMORY SUPPORT

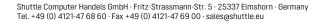
■ 2x 260-pin SO-DIMM slot ■ Supports DDR4-3200/2666/2400 max. 2x 32 GB

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Product	Chip	HDMI	DP	Displays	LAN (Intel)	M.2-2280 Slot	COM	Card reader	DC-In	VESA Mount	UPC Code
DH610S	H610	1	1	max. 2 *)	1G	PCIe v3.0 X4	—	_	19V	-	887993005126
DH610	H610	1	2	max. 3	1G+2.5G	PCIe v3.0 X4	2	-	12V + 19V	included	887993005119
DH670	H670	2	2	max. 4	2x 1G	PCIe v4.0 X4	2	Yes	19V	included	887993004983
DH670V2	H670	2	2	max. 4	2x 2.5G	PCIe v4.0 X4	2	_	19V	included	887993005942

*) max. 3 displays with optional VGA port (accessory PVG01)

**) Note: The Shuttle XPC DH610S supports Intel Core processors of the 13th generation "Raptor Lake-S" starting with firmware/BIOS version DH610100.201, which has been available since March 2023. During the transition phase Shuttle XPCs still come with an older firmware/BIOS version and must first be updated with the help of a Gen 12 processor "Alder Lake-S".





PRODUCT SPECIFICATIONS

PRODUCT FEATURES



Only 4.3 cm tall

Robust, stylish and particularly small

You should have held it in your own hands to see how small it actually is. At barely a volume of 1.35 litres, its steel chassis gives it the appropriate stability required for professional applications such as digital signage. Despite its dimensions of 19 x 16.5 x 4.3 . cm (LWH), the overall system performance is very high thanks to support of Intel Core desktop processors. The interior of the DH610S is very tidy too so that it won't take long to set up. Its sleek and stylish looks let it easily find a place in both home and office environments



An active dual-fan heatpipe cooling tion and system stability.

Supports extended temperature range and 24/7 operation The Shuttle XPC slim Barebone DH610S is officially approved for 24/7 permanent operation. Thanks to its efficient cooling, this PC runs highly reliably making it perfectly suitable for digital signage and POI/POS applications - even at ambient temperatures of up to 50 °C (non-condensing). Caution: For high ambient temperatures over 40 °C we strongly recommend to use SSDs.



Supports 12th Generation Intel® Core™ processors "Alder Lake-S" is the codename for Intel's 12th Generation of Intel® Core™ Desktop Processors for socket LGA1700 introduced in 2021/2022 along with the 600-Series chipsets. The 12000 series processors feature a new hybrid design combining a number of performance cores (P-cores) and efficiency cores (E-cores). Get the performance you need, where you need it - whether you're a gamer, creator, streamer, or everyday user.

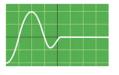


Dual 4K Display support The DH610S features two digital video outputs: one HDMI 2.0b and one DisplayPort (DP 1.4) which both can run at 4K (3840 x 2160 / 2160p) high resolution at 60 Hz frames per second. Furthermore, the DH610S supports an optional D-Sub/VGA port. The PC supports a maximum of three displavs.











One M.2-Slot for SSD cards The M.2-2280 slot supports one M.2 SSD storage card with NVMe PCIe 3.0 X4 or SATA interface. Type 2280 means, it supports the usual M.2 cards with a width of 22 mm and a length of 80 mm, but also 2242 and 2260 standard cards are supported.

Intel Network Function The Shuttle XPC slim Barebone DH610S supports Gigabit LAN with Intel network adapter, which is popular for their excellent performance and driver compatibility and is the preferred choice for professional environments.

VESA mount (optional) The optional 75/100mm VESA mount PV04 allows for installation on to walls or monitors which is particularly interesting for the industry segment, company buildings and public institutions. In addition, the chassis bears numerous threaded holes (M3) enabling it to be fitted almost anywhere.

Power on after Power fail The BIOS setup provides a "Power-On after Power Fail" function that can be found under "Power Management Configuration". As the name indicates, this function determines the PC's behaviour after power failure: (1) unconditional power on, (2) restore former status (3) keep system turned off (4) Power-On by LAN or (5) Power-On by Real-Time-Clock. As a matter of the nature of this function, it may fail after short power failures. This is why the DH610S also comes with a hardware-based solution. By removing Jumper JP2 (see image) the system will start unconditionally once power is applied.

External power button by separate remote line

If, because of space constraints (e.g. in case of fixed installation), the machine cannot be switched on by pressing the front power button, it can be powered on by a separate remote line. You will find an appropriate four-pin connector at the back panel of the DH610S (pitch 2.54 mm). Furthermore, this connector provides a Clear CMOS function and +5V DC voltage supply for external devices.

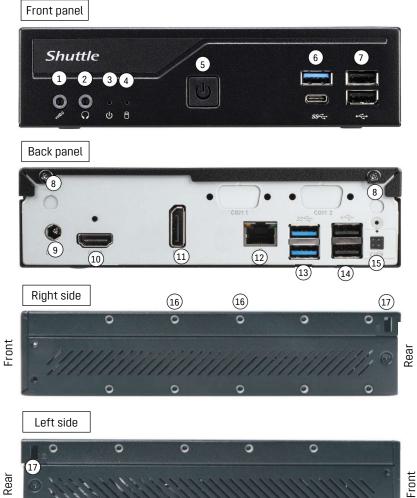
+5V voltage (2) Clear CMOS (1)

(4) Power Button (3) Ground



Shuttle[®]

Front and Back Panel



- 1. Microphone input
- 2. Headphones output
- 3. LED indicator for power state
- 4. LED indicator for storage activity
- 5. Power button
- 6. 2x USB 3.2 Gen 1 port (1x Type-C)
- 7. 2x USB 2.0
- 8. 2x WLAN perforation
- 9. DC-in connector for power adapter
- 10. HDMI 2.0b port
- 11. DisplayPort 1.4
- 12. RJ45 Gigabit LAN port
- 13. 2x USB 3.2 Gen 1 port
- 14. 2x USB 2.0
- 15. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage

- 16. Threaded holes (M3)
- 17. 2x hole for Kensington Lock

- 18. VESA mount (two parts)
 - Available as optional Accessory "PV04"

Rear

C



PRODUCT SPECIFICATIONS



Back View



Front View

- 1. 4-pin connector (2.54 mm pitch) for external power button, Clear CMOS button and 5V DC voltage)
- 2. 2x USB 2.0 port
- 3. 2x USB 3.2 Gen 1 port (1x Type-C)
- 4. RJ45 Gigabit LAN port
- 5. DisplayPort 1.2
- 6. HDMI 2.0a port
- 7. DC-in connector for power adapter
- 8. Connector for CMOS battery
- 9. Onboard USB-2.0-connector (4-pin)
- 10. M.2-2280M slot for SSD card
- 11. M.2-2230E slot for WLAN card
- 12. Intel H610 chipset with heat sink
- 13. Onboard VGA connector

- 14. 2x SO-DIMM memory slots
- 15. LGA1700 processor socket
- 16. Microphone input
- 17. Audio line-out for head-phones
- 18. LED indicator for power state
- 19. LED indicator for storage activity
- 20. SATA v3.0 port
- 21. Always-Power-On Jumper
- 22. 4-pin connector for cooling fan
- 23. Power button
- 24. 2x USB 3.2 Gen 1 port
- 25. 2x USB 2.0 port

PRODUCT SPECIFICATIONS

Intel Core Gen 12/13 "Alder Lake-S" or "Raptor Lake-S" Core i9 / i7 / i5 / i3, Pentium Gold or Celeron

(Intel Core Gen 13 "Raptor Lake-S is supported since BIOS

REQUIRED COMPONENTS

The following components need to be added to make it a fully-configured Mini PC



Shuttle XPC slim Barebone DH610S





2.5" Storage Drive

SATA hard disk or Solid State Disk (SSD)

Up to two DDR4-3200/2666/2400 SO-DIMM memory modules

LGA1700 Processor

Version DH610100.201)

Memory Modules

(max. height: 12.5 mm)

max. 32 GB each

TDP max. 65 W



M.2 SSD (optional) M.2-2280/2260/2242 SSD storage (SATA or PCIe/NVMe)



Operating System Windows 10/11 or Linux (64-bit only)

OPTIONAL ACCESSORIES FROM SHUTTLE









VGA port adapter PVG01 Installing PVG01 means one serial port (COM) less can be used on the back panel.

WLAN-Accessory WLN-M (802.11ac / Wifi 5) WLN-M1 (802.11ax / Wifi 6) M.2-2230 card supports WLAN and Bluetooth including 2 antennas

LTE Adapter Kit WWNO3 allows the installation of an M.2 LTE card and nano SIM card (occupies the 2.5" bay)





Vertical Stand PS02 for vertical operation

DIN-Rail Kit DIRO1 This mounting kit allows the installation on a standard 35 mm DIN-Rail

Rack Mount Kit PRMO1 2U front plate to install two 1.3L Shuttle XPCs in a 19" cabinet.

VESA Mount PV04 supports the 75/100 mm VESA standard

Shuttle Product Comparison: DH4xx versus DH6xx

MODEL	DH410S	DH410(C) DH470(C		DH610S	DH610	DH670(V2)			
PROCESSOR Support		Sockel LGA1200, TDP me "Comet Lake-S" –		Intel Core, Sockel LGA1700, TDP max. 65 W Codename "Alder Lake-S"/"Raptor Lake-S" – Gen 12/13 **)					
CHIPSET	Intel H410	Intel H410	Intel H470	Intel H610	Intel H610	Intel H670			
OS SUPPORT	Windo	ws 10/11 and Linux (6	64-bit)	Windows 10/11 and Linux (64-bit)					
MULTI-DISPLAY	max. 2	max. 2	max. 3	max. 2 **)	max. 3	max. 4			
RAM MEMORY	max. 2x 32	GB DDR4-2933/266	6 SO-DIMM	max. 2x 32 GB DDR4-3200/2666 S0-DIMM					
2.5" BAY	1x 2.5" drive bay,	SATA connector, max	k. height 12.5 mm	1x 2.5" drive bay,	1x 2.5" drive bay, SATA connector, max. height 12.5 mm				
M.2-2280 SSD SLOT	M.222801	A supports PCIe 3.0 x	4 or SATA	supports PCIe 3.0 x4 or SATA	supports PCIe 3.0 x4 or SATA	supports PCIe 4.0 x4 or SATA			
WLAN SLOT		M.2-2230E			M.2-2230E				
BUTTONS / LEDS	Power-	Button, Power LED, H	DD LED	Power-	Button, Power LED, H	DD LED			
SD CARD READER	Yes, but not with DH410C and DH470C			No	No	Yes, DH670 only			
GRAPHICS PORTS	HDMI 1.4b DP 1.2	HDMI 2.0a DP 1.2	HDMI 2.0a <mark>2x</mark> DP 1.2	HDMI 2.0b DP 1.4	HDMI 2.0b <mark>2x</mark> DP 1.4	2x HDMI 2.0b 2x DP 1.4			
USB 3.2 GEN. 2	-	-	4	-	_	4			
USB 3.2 GEN. 1	4 (1x Type-C)	4	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)	4 (1x Type-C)			
USB 2.0	4	4	-	4	4	-			
COM PORTS	-	2	2	-	2	2			
GIGABIT NETWORK	Single LAN Realtek 8111H (1G)	Dual LAN 2x Intel 210 (1G)	Dual LAN 2x Intel 210 (1G)	Single LAN Intel 219V/LM (1G)	Dual LAN Intel 225 (2.5G) Intel 219V/LM (1G)	Dual LAN 2x i210/211 (1G) DH670V2: 2x 2.5G			
AUDIO	Mic-Inpu	ıt, Line-Out (Realtek A	ALC662)	Mic-Input, Line-Out (Realtek ALC662/897/888S)					
OPTIONAL Accessories	F	AN Kit: WLN-M/WLN- Vertical Stand: PSO2 Rackmount Kit: PRMO VGA Port: PVGO1 ver Button Cable: CXF DIN-Rail Mount: DIRO1 LTE-Kit: WWNO3	1 201	WLAN Kit: WLN-M/WLN-M1 Vertical Stand: PS02 Rackmount Kit: PRM01 VGA Port: PVG01 Power Button Cable: CXP01 DIN-Rail Mount: DIR01 LTE-Kit: WWN03					
VESA MOUNT	optional PV04	supplied	supplied	optional PV04	supplied	supplied			
POWER ADAPTER		90 W / 19 V			120 W / 19 V				
DC-IN 12V SUPP.	-	Yes	-	-	Yes	-			



*) The DH410C and DH470C have no Card Reader. **) The DH610S supports 3 displays, if equipped with VGA port (accessory PVG01) **) Shuttle XPCs of the DH6xx/XH61x series support Intel Core processors of the 13th generation "Raptor Lake-S" starting with a certain firmware/BIOS version, which has been available since March 2023. During the transition phase Shuttle XPCs still come with an older firmware/BIOS version and must first be updated with the help of a Gen 12 processor "Alder Lake-S".

SHUTTLE XPC SLIM BAREBONE DH610S - SPECIFICATIONS

CHASSIS	Slim PC with black chassis made of metal Dimensions: 190 x 165 x 43 mm (LWH) = 1.35-litre Weight: 1.3 kg net and 2.1 kg gross Two holes for Kensington Locks and numerous threaded holes (M3) on both sides of the chassis
POWER ADAPTER	External 120 W power adapter (fanless) Input: 100~240 V AC, 50/60 Hz Output: 19 V DC, 6.32 A, max. 120 W DC Connector: 5.5/2.5 mm (outer/inner diameter) Remark: The DC-input of the computer supports an external power source with 19V±5%. AC mains cable: 3 pins, ca. 1.7 m length, with C5/C6 coupler (called "Mickey Mouse" or "Clover-leaf") for the power adapter and CEE-7/7 plug with earth-contact (type E+F) for the power outlet
OPERATING SYSTEM	This system comes without an operating system. It is compatible with Windows 10/11 and Linux (64-bit).
PROCESSOR SUPPORT	Processor Socket LGA1700 Supports Intel Core i9 / i7 / i5 / i3, Pentium Gold and Celeron processors Supports 12th/13th generation Intel Core processors, codename "Alder Lake-S" and "Raptor Lake-S" [9] in "Intel 7" process technology (previously Intel 10 nm Enhanced SuperFin) Supports processors with integrated graphics only [5] Maximum supported processor power consumption (TDP) = 65 W Does not support the unlock-function of Intel K-Series processors. The processor integrates PCI-Express, memory controller and the graphics engine on the same die. (Performance features depend on processor type) Please refer to the support list for detailed processor support information at global.shuttle.com.
PROCESSOR COOLING	Heatpipe processor cooling with two 60 mm fans on the upper side of the chassis
MAINBOARD / CHIPSET	Mainboard in a Shuttle form factor proprietary design for the XPC DH610S Chipset/Southbridge: Intel® H610 Passive chipset cooling with heat sink The Northbridge is integrated in the processor. Solid Capacitors for sensitive areas provide excellent heat resistance for enhanced system durability.
BIOS	AMI BIOS, SPI Interface, 16 MB Flash-EEPROM Supports Hardware Monitoring and watch dog functionality Supports Firmware-TPM (fTPM) v2.0 [3] Supports boot up from external USB flash memory Supports Unified Extensible Firmware Interface (UEFI) Supports power on after power failure [7]
MEMORY SUPPORT	2x SO-DIMM slot with 260 pins Supports DDR4-3200/2933/2666/2400/2133 (PC4-25600/23466/21300/19200/17000) SDRAM at 1.2 V Supports Dual Channel mode Supports a maximum of 32 GB per DIMM, maximum total size: 64 GB Supports two unbuffered DIMM modules (no ECC or registered)
INTEGRATED GRAPHICS	The features of the integrated Intel UHD graphics function depend on the processor type used. [5] The PC features two digital video outputs which support 1080p/60 and 2160p/60: - 1x HDMI v2.0b - 1x DisplayPort v1.4 Supports displays with 4K Ultra HD resolution at 3840 x 2160 DisplayPort and HDMI support multi-channel digital audio over the same cable. Optional analog D-Sub/VGA video output [4] Supports two independent displays with the integrated graphics function (even three with the optional VGA port)
DRIVE BAY	1x 6.35 cm / 2.5" storage bay supports one hard disk or SSD drive with SATA connector Device height: 12.5 mm (max.)
SATA CONNECTORS	1x Serial-ATA III, 6 Gb/s (600 MB/s) bandwidth With Serial-ATA power connector (onboard)

M.2-2280M SSD SLOT	The M.2 2280M slot provides the following interfaces: - PCI-Express Gen. 3.0 X4, supports NVMe - SATA v3.0 (max. 6 Gbps) It supports M.2 cards with a width of 22 mm and a length of 42, 60 or 80 mm (type 2242, 2260, 2280). Supports M.2 SSDs with SATA or PCI-Express interface
M.2-2230E SLOT FOR Wlan Cards	Interfaces: PCI-Express Gen. 2.0 X1 and USB 2.0 Supports M.2 cards with a width of 22 mm and a length of 30 mm (type 2230) Supports WLAN expansion cards (optional Shuttle accessory: WLN-M/M1)
AUDIO	Audio Realtek® ALC 897/662/888S High-Definition Audio Two analog audio connectors (3.5 mm) on the front panel: 1) 2-channel line-out (headphones) 2) microphone input Digital multi-channel audio output: by HDMI and DisplayPort
LAN CONTROLLER	RJ45 network port with two status LEDs each Intel 219V/LM network chip supports 10 / 100 / 1.000 MBit/s data transfer rate Supports WAKE ON LAN (WOL) Supports network boot by Preboot eXecution Environment (PXE)
FRONT PANEL Connectors	Microphone input Audio Line-out (headphones) 1x USB 3.2 Gen 1 Type A (blue) 1x USB 3.2 Gen 1 Type C 2x USB 2.0 Type A (black) Power button Power LED (blue) HDD LED (yellow)
BACK PANEL Connectors	1x HDMI 2.0b connector [1] 1x DisplayPort 1.4 connector (DP) [2] Optional: 1x D-Sub VGA connector (Accessory PVG01 [4]) 2x USB 3.2 Gen 1 Type A (blue) 2x USB 2.0 Type A (black) 1x RJ45 Gigabit LAN Port 1x DC-input connector for external power adapter (supports 19V±5%) 1x 4-pin connector (2.54 mm pitch) supports: - external power on button - Clear CMOS function - +5V DC voltage for external components 2x perforation for optional Wireless LAN antennas 2x hole for Kensington Lock
OTHER ONBOARD Connectors	1x jumper for power-on-after-power-fail (hardware solution) [7] 1x analog VGA graphics output CN6 (2x 10-pin, 1 mm pitch) [4] 1x USB 2.0 (4-pin) for optional accessory WWN03 (LTE kit) 1x fan connector (4-pin) occupied by the cooling system 1x connector for CMOS battery (occupied)
SUPPLIED ACCESSORIES	Multi-language user guide (EN, DE, FR, ES, JP, KR, SC, TC) Four screws M3 x 4 mm (to mount a 2.5" storage device into the bay) Two screws M3 x 5 mm (silver colour, to mount two M.2 cards) Driver DVD (Windows 64-bit) Serial ATA cable for 2.5" drive including power cable External 120 W power adapter with power cord Protection cap for CPU socket (do not use if heatpipe or fan is mounted) Heatsink compound
OPTIONAL ACCESSORIES	 PVG01: optional D-Sub VGA video output [4] WLN-M/WLN-M1: WLAN module in M.2-2230 format supports WLAN and Bluetooth with two external antennas. WWN03: LTE adapter kit with antennas, but without LTE card [8] PS02: Stand for vertical operation CXP01: adapter cable for external power button PRM01: 2U rack mount front plate for two Shuttle XPC slim PCs DIR01: DIN-Rail mounting kit PV04: VESA mount

ENVIRONMENTAL SPECIFICATIONS	Operating temperature range: 0~50 °C [6] Relative humidity, non-condensing: 10~90 %
CERTIFICATIONS / COMPLIANCE	EMI: FCC, CE, BSMI, RCM, VCCI Safety: ETL, CB, BSMI Other: RoHS, Energy Star, ErP
CONFORMITY	 This device is classed as a technical information equipment (ITE) in class B and is intended for use in living room and office. The CE-mark approves the conformity by the EU directives: (1) 2004/108/EC relating to electromagnetic compatibility (EMC), (2) 2006/95/EC relating to Electrical Equipment designed for use within certain voltage limits (LVD), (3) 2009/125/EC relating to ecodesign requirements for energy-related products (ErP)

[1] HDMI output supports DVI-D with optional adapter

[2] How to convert DisplayPort into HDMI/DVI

The DisplayPort output can be converted to HDMI or DVI by an additional, passive adapter cable. For example:

DELOCK 82590: 1 m, DisplayPort (male, 20p) to HDMI-A (male, 19p)

DELOCK 82435: 5 m, DisplayPort (male, 20p) to DVI-D (male, 24p)

The integrated graphics automatically detects the connected display and puts out the appropriate electric signal - either through DisplayPort (without an adapter) or HDMI/DVI (with an adapter).

However, a monitor with a DisplayPort connector cannot be connected to the HDMI port with a simple, passive adapter.

[3] TPM Function

This product features Firmware-TPM (fTPM) v2.0. Besides this, it is prepared for a hardware TPM chip which can be fitted by factory on request, if required.

[4] Optional D-Sub/VGA connector

The mainboard features one analog graphics port CN6 on the mainboard. This signal can be lead to the outside as a 15-pin D-Sub VGA connector on the back panel by using the optional adapter PVG01. However doing so means one serial port (COM) less can be used on the back panel. The integrated graphics supports a maximum of four displays simultaneously.

[5] Intel processors without integrated graphics (ID ends with "F", e.g. Core i7-12700F) are not compatible.

[6] Operating temperature

For high ambient temperatures over 40 °C we strongly recommend to use SSDs (supporting at least 70 °C) and rugged SO-DIMM memory modules with a temperature range of up to 95 °C.

[7] Power on after power fail

The BIOS setup provides a "Power-On after Power Fail" function that can be found under "Power Management Configuration". As the name indicates, this function determines the PC's behaviour after power failure: (1) unconditional power on, (2) restore former status or (3) keep system turned off. As a matter of the nature of this function, it may fail after short power failures. This is why the DH610S also comes with a hardware-based solution. By removing Jumper JP2 (on the mainboard behind the power button) the system will start unconditionally once power is supplied.

[8] Optional Accessory WWN03 (LTE kit)

The Shuttle XPC accessory WWN03 allows this PC to be upgraded with an LTE/4G function for mobile network. The LTE card will occupy the 2.5" bay, so you will have to use an M.2 SSD as a mass storage device. The required LTE/4G card in M.2-3042 format and an activated Nano SIM card is not included in the scope of delivery.

[9] The Shuttle XPC DH610S supports Intel Core processors of the 13th generation "Raptor Lake-S" starting with firmware/BIOS version DH610100.201, which has been available since March 2023. During the transition phase Shuttle XPCs still come with an older firmware/BIOS version and must first be updated with the help of a Gen 12 processor "Alder Lake-S".

12TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1700 10 nm "Alder Lake S" processor overview (Date: January 2022) Processors with a TDP of more than 65W and processors without graphics function (ID ends with "F") are not supported (marked in red).

PROCESSOR	MODEL	P-CORES/	P-CORES	E-CORES	E-CORES	SMART	BASE	MEMORY	GRAPHICS ENGINE
	10000//	THREADS	CLOCK/Turbo	0	CLOCK/Turbo	CACHE	TDP	SUPPORT	(MAX. CLOCK)
	12900 <u>K</u>	8/16	3.2 – 5.1 GHz	8	2.4 – 3.9 GHz	30 MB	125 W	DDR4-3200	UHD 770 (1.55 GHz)
	12900 <u>KF</u>	8/16	3.2 – 5.1 GHz	8	2.4 – 3.9 GHz	30 MB	125 W	DDR4-3200	None
Core™ i9	12900	8/16	2.4 - 5.0 GHz	8	1.8 – 3.8 GHz	30 MB	65 W	DDR4-3200	UHD 770 (1.55 GHz)
	12900 <u>F</u>	8/16	2.4 – 5.0 GHz	8	1.8 – 3.8 GHz	30 MB	65 W	DDR4-3200	None
	12900T	8/16	1.4 – 4.8 GHz	8	1.0 – 3.6 GHz	30 MB	35 W	DDR4-3200	UHD 770 (1.55 GHz)
	12700 <u>K</u>	8/16	3.6 - 4.9 GHz	4	2.7 – 3.8 GHz	25 MB	125 W	DDR4-3200	UHD 770 (1.50 GHz)
	12700 <u>KF</u>	8/16	3.6 – 4.9 GHz	4	2.7 – 3.8 GHz	25 MB	125 W	DDR4-3200	None
Core™ i7	12700	8/16	2.1 - 4.9 GHz	4	1.6 – 3.6 GHz	25 MB	65 W	DDR4-3200	UHD 770 (1.50 GHz)
	12700 <u>F</u>	8/16	2.1 – 4.9 GHz	4	1.6 – 3.6 GHz	25 MB	65 W	DDR4-3200	None
	12700T	8/16	1.4 - 4.6 GHz	4	1.0 - 3.4 GHz	25 MB	35 W	DDR4-3200	UHD 770 (1.50 GHz)
	12600 <u>K</u>	6 / 12	3.7 - 4.9 GHz	4	2.8 - 3.6 GHz	20 MB	125 W	DDR4-3200	UHD 770 (1.45 GHz)
	12600 <u>KF</u>	6 / 12	3.7 - 4.9 GHz	4	2.8 - 3.6 GHz	20 MB	125 W	DDR4-3200	None
	12600	6 / 12	3.3 - 4.8 GHz	-	-	18 MB	65 W	DDR4-3200	UHD 770 (1.45 GHz)
	12600T	6 / 12	2.1 - 4.6 GHz	-	-	18 MB	35 W	DDR4-3200	UHD 770 (1.45 GHz)
Core™ i5	12500	6 / 12	3.0 - 4.6 GHz	-	-	18 MB	65 W	DDR4-3200	UHD 770 (1.45 GHz)
	12500T	6 / 12	2.0 - 4.4 GHz	-	-	18 MB	35 W	DDR4-3200	UHD 770 (1.45 GHz)
	12400	6 / 12	2.5 - 4.4 GHz	-	-	18 MB	65 W	DDR4-3200	UHD 730 (1.45 GHz)
	12400 <u>F</u>	6 / 12	2.5 - 4.4 GHz	-	-	18 MB	65 W	DDR4-3200	None
	12400T	6/12	1.8 – 4.2 GHz	-	-	18 MB	35 W	DDR4-3200	UHD 730 (1.45 GHz)
	12300	4/8	3.5 - 4.4 GHz	-	-	12 MB	60 W	DDR4-3200	UHD 730 (1.45 GHz)
	12300T	4/8	2.3 - 4.2 GHz	-	-	12 MB	35 W	DDR4-3200	UHD 730 (1.45 GHz)
Core™ i3	12100	4/8	3.3 - 4.3 GHz	-	-	12 MB	60 W	DDR4-3200	UHD 730 (1.45 GHz)
	12100 <u>F</u>	4/8	3.3 - 4.3 GHz	-	-	12 MB	58 W	DDR4-3200	None
	12100T	4/8	2.2 - 4.1 GHz	-	-	12 MB	35 W	DDR4-3200	UHD 730 (1.40 GHz)
Pentium®	G7400	2/4	3.7 GHz	-	_	6 MB	46 W	DDR4-3200	UHD 710 (1.35 GHz)
Gold	G7400T	2/4	3.1 GHz	-	-	6 MB	35 W	DDR4-3200	UHD 710 (1.35 GHz)
	G6900	2/2	3.4 GHz	-	-	4 MB	46 W	DDR4-3200	UHD 710 (1.30 GHz)
Celeron®	G6900T	2/2	2.8 GHz	-	-	4 MB	35 W	DDR4-3200	UHD 710 (1.30 GHz)

K = unlocked, T = Power optimized lifestyle, F = without integrated graphics, Base TDP = Base Thermal Design Power (max. Base Power Consumption).

Note: The Shuttle XPC slim Barebone DH610S does not support the Unlock-function of Intel K-Series processors. P-Cores: Performance-Cores, E-Cores: Efficient-Cores

Core Clock: the listed core frequency ranges from Base Frequncy to Turbo Frequency (Turbo Boost 3.0 Frequency is not mentioned here) Base TDF: Processor Base Power dissipation that the processor is validated to not exceed at Base Frequency (Max. Turbo Power is not mentioned here) Please refer to the support list for detailed processor support information at global.shuttle.com.

13TH GENERATION INTEL CORE DESKTOP PROCESSOR FAMILY

Socket LGA1700, Intel 7 / 10 nm, "Raptor Lake S" processor overview (Date: January 2023) Processors with a TDP of more than 65W and processors without graphics function (ID ends with "F") are not supported (marked in red).

Note: The Shuttle XPC DH610S supports Intel Core processors of the 13th generation "Raptor Lake-S" starting with firmware/BIOS version DH610100.201, which has been available since March 2023. During the transition phase Shuttle XPCs still come with an older firmware/BIOS version and must first be updated with the help of a Gen 12 processor "Alder Lake-S".

PROCESSOR	MODEL	P-CORES/ Threads	P-CORES CLOCK/Turbo	E-CORES	E-CORES CLOCK/Turbo	SMART CACHE	BASE TDP	MEMORY Support	GRAPHICS ENGINE (MAX. CLOCK)
Core™ i9	13900 <u>k</u> s	8/16	3.2 - 6.0 GHz	16	2.4 - 4.3 GHz	36 MB	150 W	DDR4-3200	UHD 770 (1.65 GHz)
	13900 <u>K</u>	8/16	3.0 – 5.8 GHz	16	2.0 - 4.3 GHz	36 MB	125 W	DDR4-3200	UHD 770 (1.65 GHz)
	13900 <u>KF</u>	8/16	3.0 – 5.8 GHz	16	2.0 - 4.3 GHz	36 MB	125 W	DDR4-3200	None
	13900	8/16	2.0 - 5.2 GHz	16	1.5 – 4.2 GHz	36 MB	65 W	DDR4-3200	UHD 770 (1.65 GHz)
	13900 <u>F</u>	8/16	2.0 - 5.2 GHz	16	1.5 – 4.2 GHz	36 MB	65 W	DDR4-3200	None
	13900T	8/16	1.1 – 5.1 GHz	16	0.8 - 3.9 GHz	36 MB	35 W	DDR4-3200	UHD 770 (1.65 GHz)
	13700 <u>K</u>	8/16	3.4 - 5.4 GHz	8	2.5 – 4.2 GHz	30 MB	125 W	DDR4-3200	UHD 770 (1.60 GHz)
	13700 <u>KF</u>	8/16	3.4 - 5.4 GHz	8	2.5 - 4.2 GHz	30 MB	125 W	DDR4-3200	None
Core™ i7	13700	8/16	2.1 – 5.1 GHz	8	1.5 – 4.1 GHz	30 MB	65 W	DDR4-3200	UHD 770 (1.60 GHz)
	13700 <u>F</u>	8/16	2.1 – 5.1 GHz	8	1.5 – 4.1 GHz	30 MB	65 W	DDR4-3200	None
	13700T	8/16	1.4 – 4.8 GHz	8	1.0 - 3.6 GHz	30 MB	35 W	DDR4-3200	UHD 770 (1.60 GHz)
	13600 <u>K</u>	6 / 12	3.5 – 5.1 GHz	8	2.6 - 3.9 GHz	20 MB	125 W	DDR4-3200	UHD 770 (1.50 GHz)
	13600 <u>KF</u>	6 / 12	3.5 - 5.1 GHz	8	2.6 - 3.9 GHz	20 MB	125 W	DDR4-3200	None
	13600	6 / 12	2.7 – 5.0 GHz	8	2.0 - 3.7 GHz	24 MB	65 W	DDR4-3200	UHD 770 (1.55 GHz)
	13600T	6 / 12	1.8 – 4.8 GHz	8	1.3 - 3.4 GHz	24 MB	35 W	DDR4-3200	UHD 770 (1.55 GHz)
Core™ i5	13500	6 / 12	2.5 - 4.8 GHz	8	1.8 – 3.5 GHz	24 MB	65 W	DDR4-3200	UHD 770 (1.55 GHz)
	13500T	6 / 12	1.6 – 4.6 GHz	8	1.2 – 3.2 GHz	24 MB	35 W	DDR4-3200	UHD 770 (1.55 GHz)
	13400	6 / 12	2.5 - 4.6 GHz	4	1.8 - 3.3 GHz	20 MB	65 W	DDR4-3200	UHD 730 (1.55 GHz)
	13400 <u>F</u>	6 / 12	2.5 - 4.6 GHz	4	1.8 – 3.3 GHz	20 MB	65 W	DDR4-3200	None
	13400T	6 / 12	1.3 - 4.4 GHz	4	1.0 - 3.0 GHz	20 MB	35 W	DDR4-3200	UHD 730 (1.55 GHz)
	13100	4/8	3.4 - 4.5 GHz	-	-	12 MB	60 W	DDR4-3200	UHD 730 (1.50 GHz)
Core™ i3	13100 <u>F</u>	4/8	3.4 - 4.5 GHz	-	-	12 MB	58 W	DDR4-3200	None
	13100T	4/8	2.5 - 4.2 GHz	-	-	12 MB	35 W	DDR4-3200	UHD 730 (1.50 GHz)

K = unlocked, T = Power optimized lifestyle, F = without integrated graphics, Base TDP = Base Thermal Design Power (max. Base Power Consumption).

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